



100% Material Declaration Data Sheet FG456

PK154 (v1.2) September 21, 2006

Material Declaration Data Sheet

Average Weight: 1.6871 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0604	3.58%
	Silicon	7440-21-3	100.00		0.0604	
Die Attach Material					0.0062	0.37%
	Silver	7440-22-4	78.00		0.0048	
	Resin	Trade Secret	22.00		0.0014	
Mold Compound					0.7340	43.51%
	Epoxy Resins	Trade Secret	12.00		0.0881	
	SiO2	60676-86-0	88.00	Filler	0.6459	
Laminate					0.3777	22.39%
	Laminate	Trade Secret	61.64		0.2328	
	Solder Mask	Trade Secret	17.53		0.0662	
	Copper	7440-50-8	16.18	Metal Layer	0.0611	
	Nickel	7440-02-0	3.94	Metal Layer	0.0149	
	Gold	7440-57-5	0.74	Metal Layer	0.0028	
Bond Wire					0.0263	1.56%
	Gold	7440-57-5	99.00		0.026058410	
	Silver	7440-22-4	0.0025		0.000000658	
	Copper	7440-50-8	0.0005		0.000000132	
	Iron	7439-89-6	0.0005		0.000000132	
	Calcium	7440-70-2	0.0020		0.000000526	
	Palladium	7440-05-3	0.9900		0.000260584	
	Magnesium	7439-95-4	0.0005		0.000000132	
Solder Balls					0.4825	26.62%
	Tin	7440-31-5	63.00		0.303975	
	Lead	7439-92-1	37.00		0.178525	

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1

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
9/21/06	1.2	Updated component descriptions.